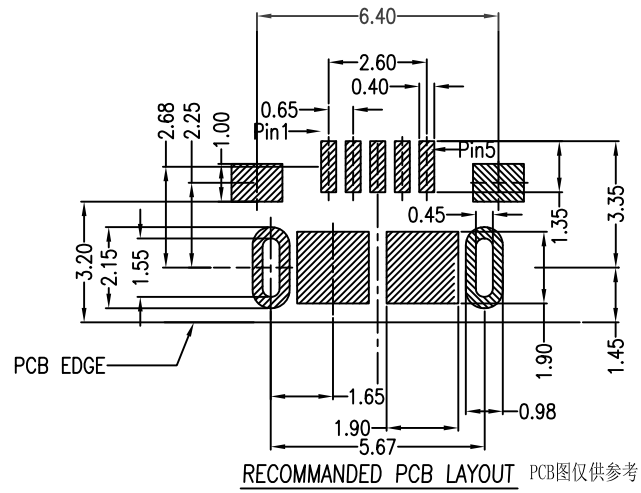
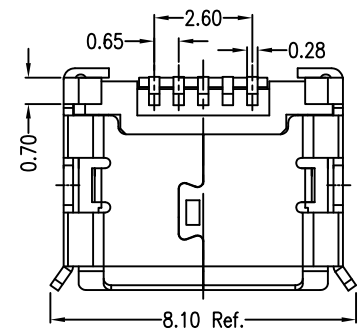
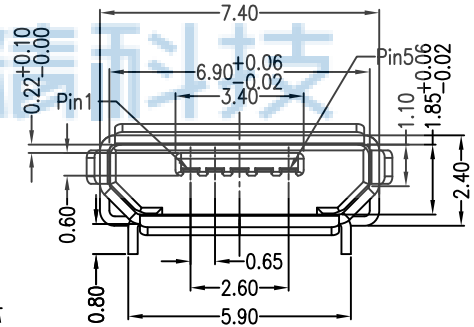
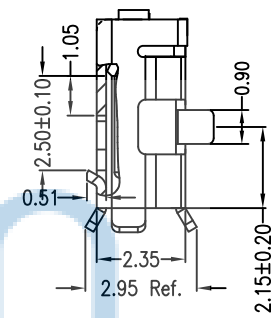
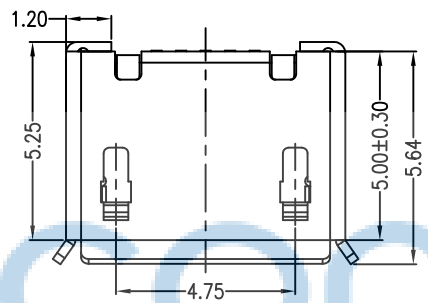
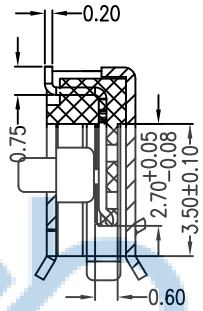
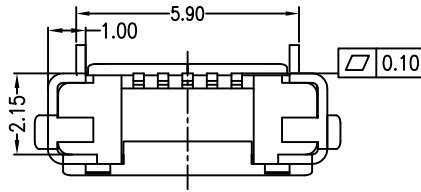


REV.	ECN NO.	CONTENT	DATE	ENGINEER
AO			2023 20/04	



Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.20mm contact area Au flash plating;
- 1.3 Shell:copper or SUS304,t=0.25mm Sn planting 60U" min.

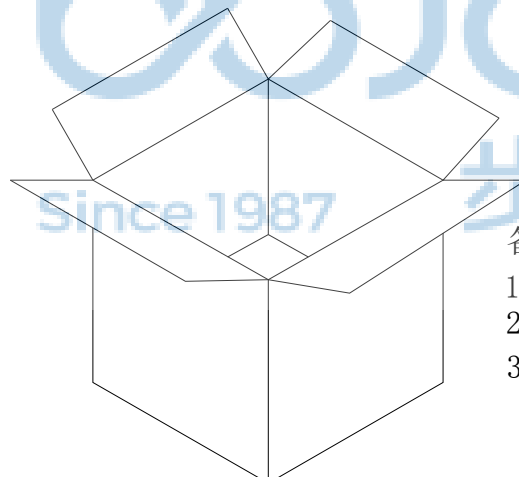
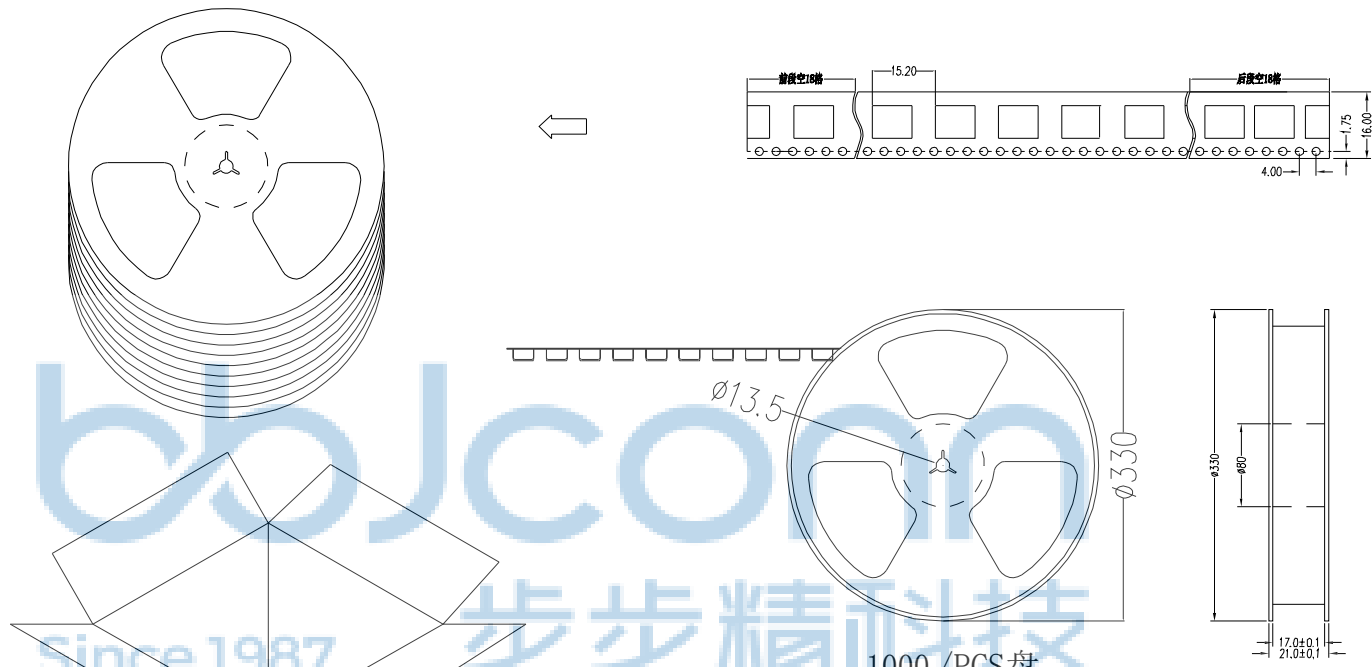
2.Specification:

- 2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.
- 2.7 Temperature range: -30°C~80°C
- 2.8 Solderability: 90% area min;



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APPD.	JM_Zheng	23/05/02	PJ. NO.: MC.01.21-21-1003		SIZE: A4
CHKD.	LYX	23/05/02	FINISH: SEE NOTES		MAT'L.: SEE NOTES
PDWG.NO:	0113-1	DR.	SGF	23/05/02	SCALE: N/A REV.: A3 UNIT: mm PAGE: 1/1

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0			2023 20/04	



1000 /PCS盘

备注：
 1. 包装数量：1000 /PCS/盘，10盘/箱或15盘/箱。
 2. 包装袋长度：每盘前后各空10-20个空格，中间包装。
 3. 材质：
 载体：聚丙烯（PS），阻抗 $10^{6-9} \Omega$
 上带：聚乙烯（PET），阻抗 $10^{6-11} \Omega$
 卷盘：聚苯乙烯。
 纸箱规格：345*345*23MM
 纸箱规格：345*345*35MM



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.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X': ±3" X'': ±2" XX': ±1"	
P.J. NO.: MC.01.21-21-1003 SIZE: A4 DRW NO.: FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A3 UNIT: mm PAGE: 1/1			